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PRODUCT NAME	DCAY0000	VERSION	d02	
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SPECIFICATION

CUSTOMER PART NO. : 273109000012

SPEC NO. : SP03AE09150-0040

PART NO. : 03A58D5G00J011T

PRODUCT NAME : DCAY0000

DESCRIPTION : Dielectric Chip Antenna
(5.0x2.5x0.55 mm)
RoHS Compliant Product

REVISION STATUS

VERSION	DATE	PAGE	REVISION DESCRIPTION	PREPARED	CHECKED	APPROVED
d01	2024.06.26	Whole	New Issued	翁秀惠	馬得淞	張敦信、吳佳宗
d02	2024.07.18	P.5	Add Data	翁秀惠	馬得淞	張敦信、吳佳宗

Prepared By	Checked By	Approved By
翁秀惠	馬得淞	張敦信 吳佳宗

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CIROCOMM TECHNOLOGY

PART NUMBER : 03A58D5G00J011T

1. SCOPE

This specification covers the Dielectric chip Antenna for 868 / 915 MHz Applications.

2. Name of the product

This product is named "Dielectric Chip Antenna".

3. Electrical characteristics

3-1 Electrical characteristics of antenna

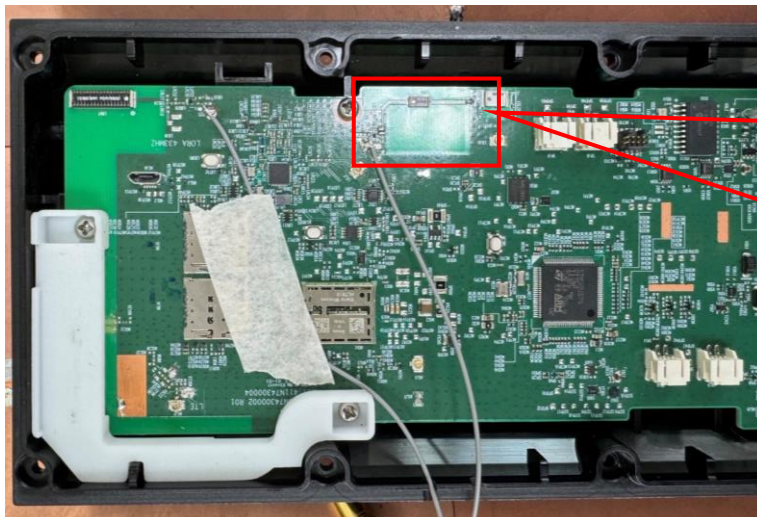
The antenna has the electrical characteristics given in Table 1 under the *cirocomm* standard installation conditions shown in the figure of Evaluation Board.

Table 1

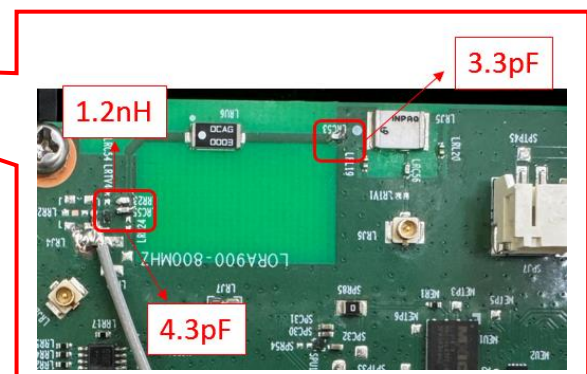
No.	Parameter	Specification
1	Working Frequency	868 / 915 MHz
2	Dimension	5.0x2.5x0.55 mm
3	Azimuth	Omni-directional
4	Polarization	Linear
5	Impedance	50 Ω
6	Operating Temperature	-40~105°C

*Actual value will depend on customer device.

Environment



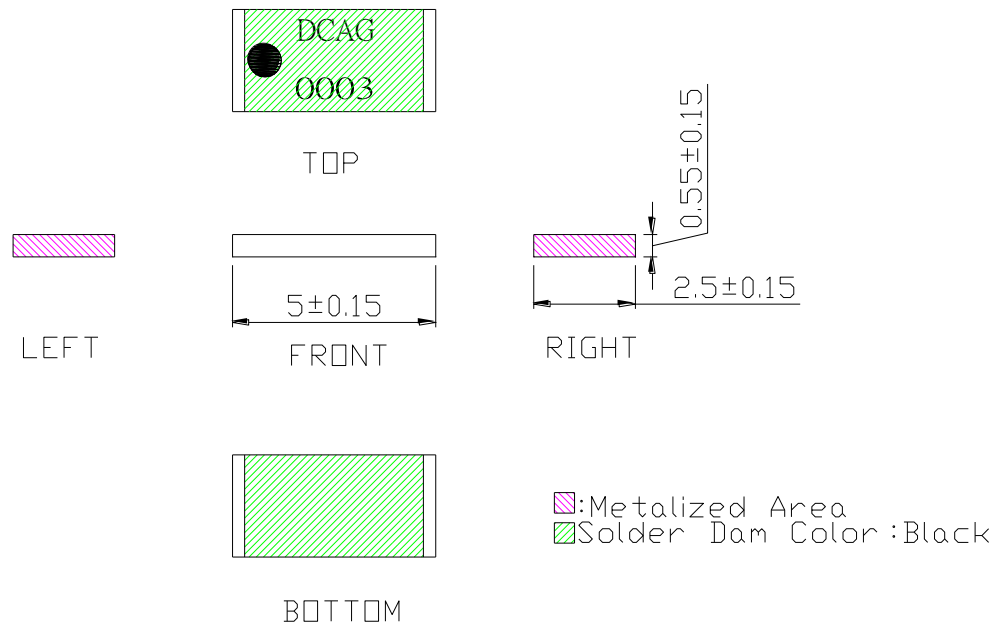
Matching Circuit



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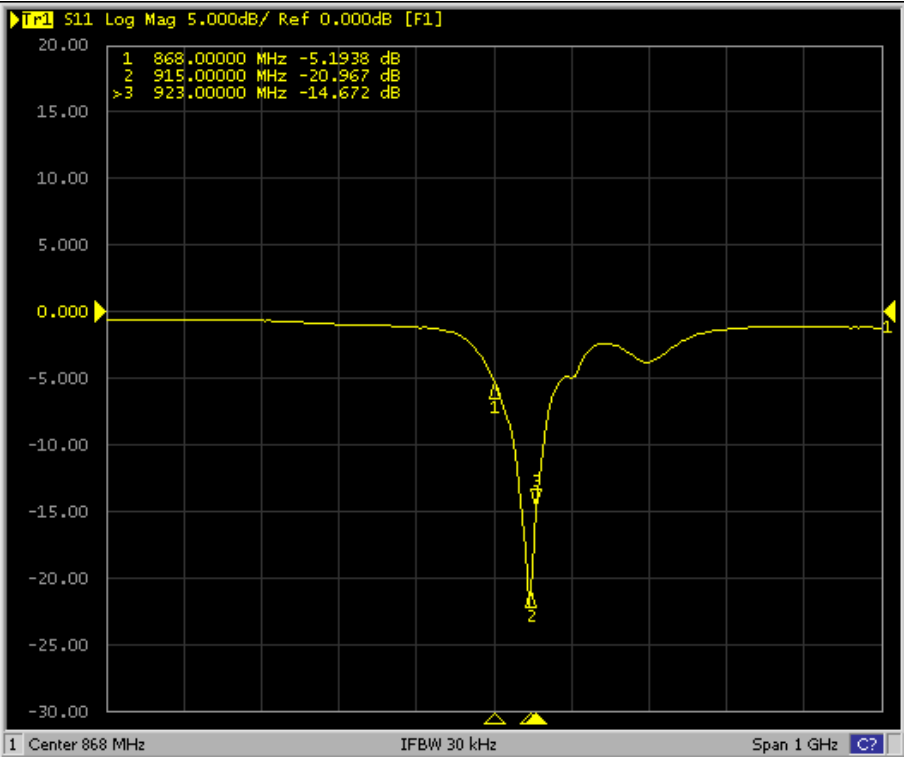
4. Antenna

4-1. Antenna Dimension



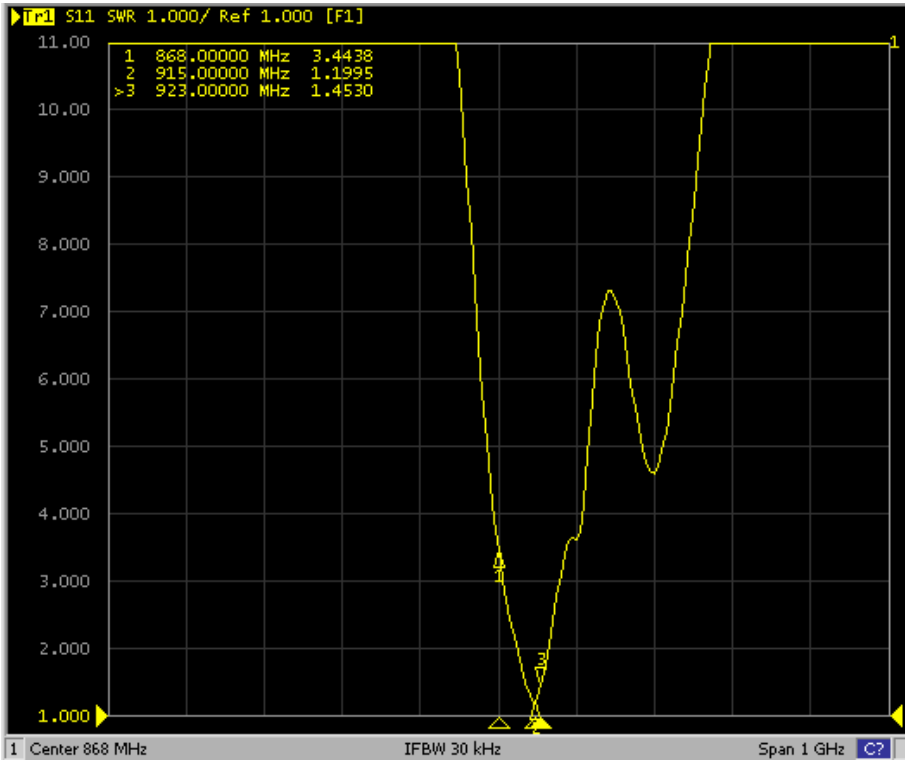
Unit: mm

4-2. Return Loss

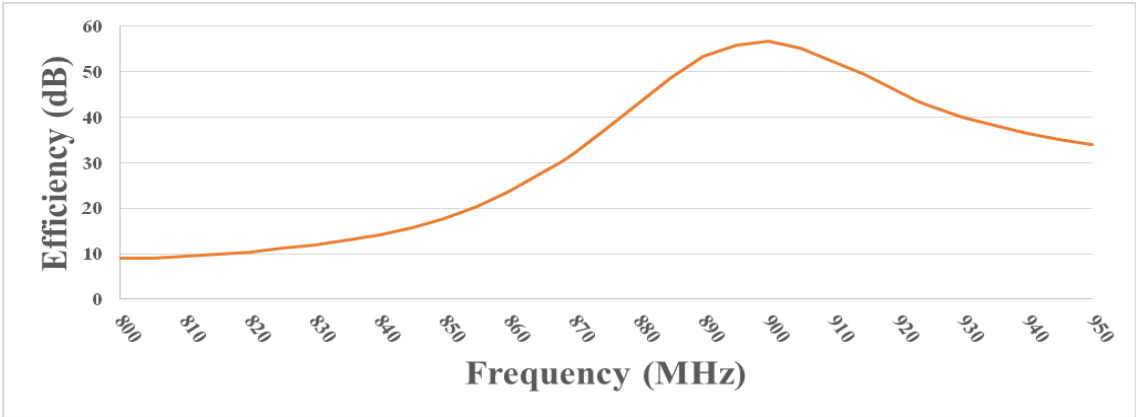


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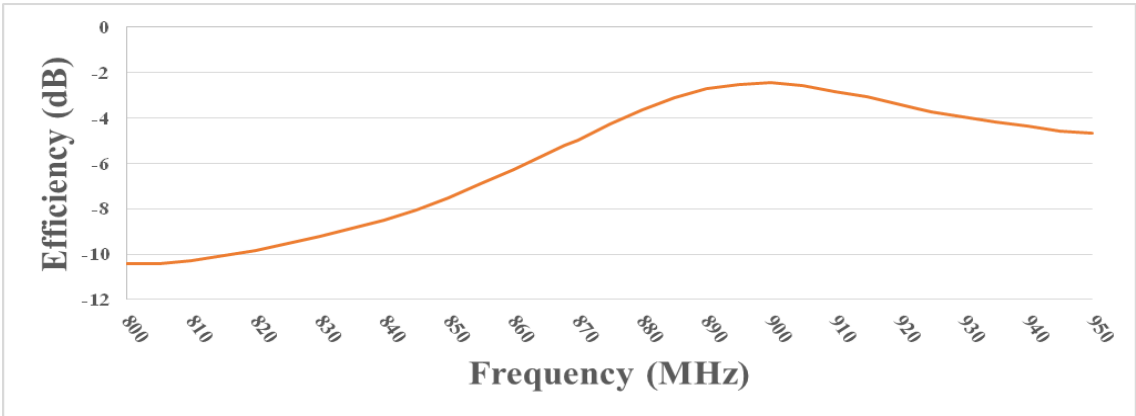
SWR



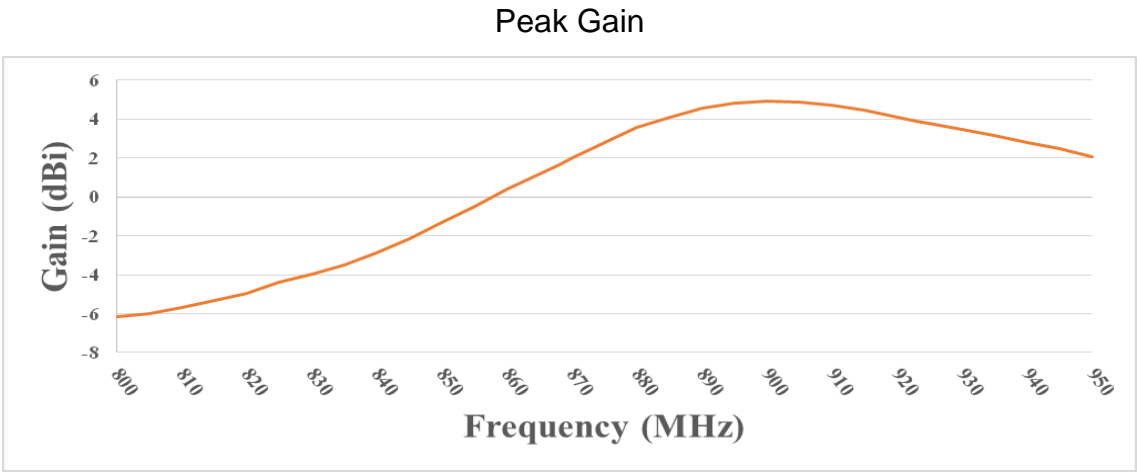
Efficiency



Average Gain

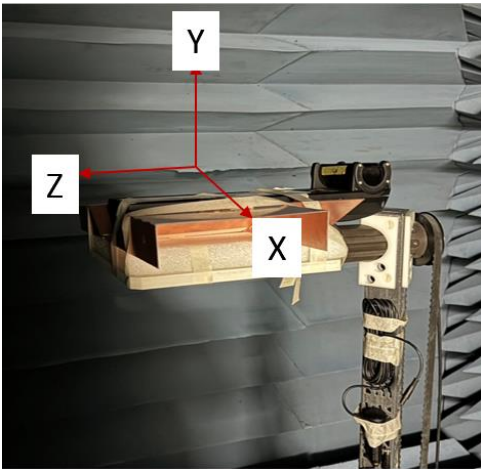


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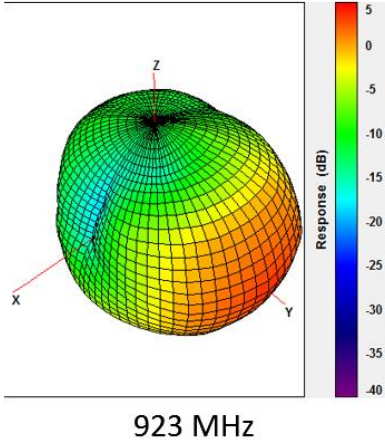
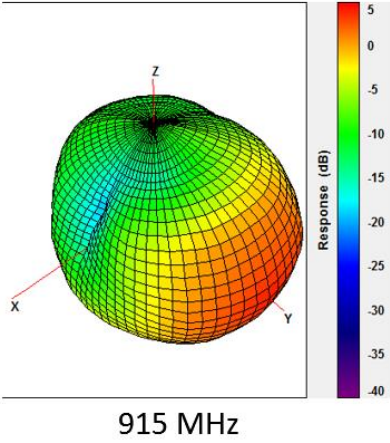
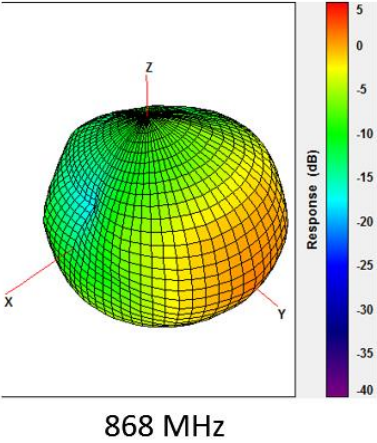


Frequency (MHz)	868	915	904.5	923
Efficiency(%)	30.16	49.41	55.18	43.68
Average Gain(dB)	-5.21	-3.06	-2.58	-3.6
Peak Gain(dBi)	1.66	4.46	4.87	3.91

4-3. Electrical performance

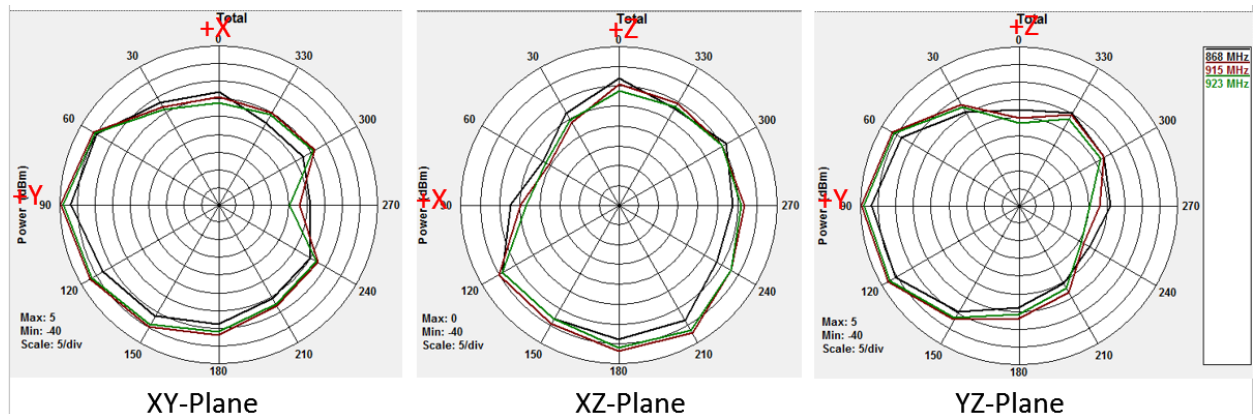


3D Radiation Pattern



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2D Radiation Pattern



5. Environmental conditions

5-1 Operating conditions

The antenna has the electrical characteristics given in Tables 1 in the temperature range of -40°C to $+85^{\circ}\text{C}$ and under the environmental conditions of $+40^{\circ}\text{C}$ and 0-95% relative humidity.

5-2 Storage temperature range

The storage temperature range of product is -40°C to $+85^{\circ}\text{C}$.

6. Reliability tests

6-1 Low-temperature test

Expose the specimen to -40°C for 16 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

6-2 High-temperature test

Expose the specimen to $+85^{\circ}\text{C}$ for 16 hours and then to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

6-3 High-temperature/high-humidity test

Subject the object to the environmental conditions of $+85^{\circ}\text{C}$ and 90-95% relative humidity for 96 hours, then expose it to normal temperature/humidity for 24 hours or more. After this test, examine its appearance and functions.

6-4 Thermal shock test

Subject the object to cyclic temperature change (-40°C , 30 minutes \leftrightarrow $+85^{\circ}\text{C}$, 30 minutes) for 5 cycles, then expose to normal temperature/humidity for 24 hours or more.

6-5 Vibration test

6-5-1 Sinusoidal vibration test

Subject the object to vibrations of 5 to 200 to 5Hz swept in 10 minutes, 4.5G at maximum (2mm amplitude), in X and Y directions for two hours each and in Z direction for four hours. After this test, examine its appearance functions.

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6-5-2 Vibration test in packaged condition

Subject the object, which is packaged as illustrated, to vibrations of 15 to 60 to 15Hz swept in 6 minutes, 4G at maximum (2mm amplitude at maximum), applied in X, Y and Z directions for two hours each, i.e. six hours in total. After this test, examine its appearance and functions.

6-6 Free fall test in packaged condition

Drop the object, which is packaged as illustrated, to a concrete surface from the height of 90 cm, on one corner, three edges and six faces once each, i.e. 10 times in total. After this test, examine its appearance and functions.

6-7 Soldering heat resistance test

The lead pins of the unit are soaked in solder bath at $260 \pm 5^{\circ}\text{C}$ for 10 seconds. After this test, examine its appearance and functions.

6-8 Adhesion test

The device is subjected to be soldered on test PCB. Then apply 0.5Kg (5N) of force for 5 ± 1 seconds in the direction of parallel to the substrate. (The soldering should be done by reflow and be conducted with care so that the soldering is uniform and free of defect by stress such as heat shock).

7. Warranty

If any defect occurs from the product during proper use within a year after delivery, it will be repaired or replaced free of charge.

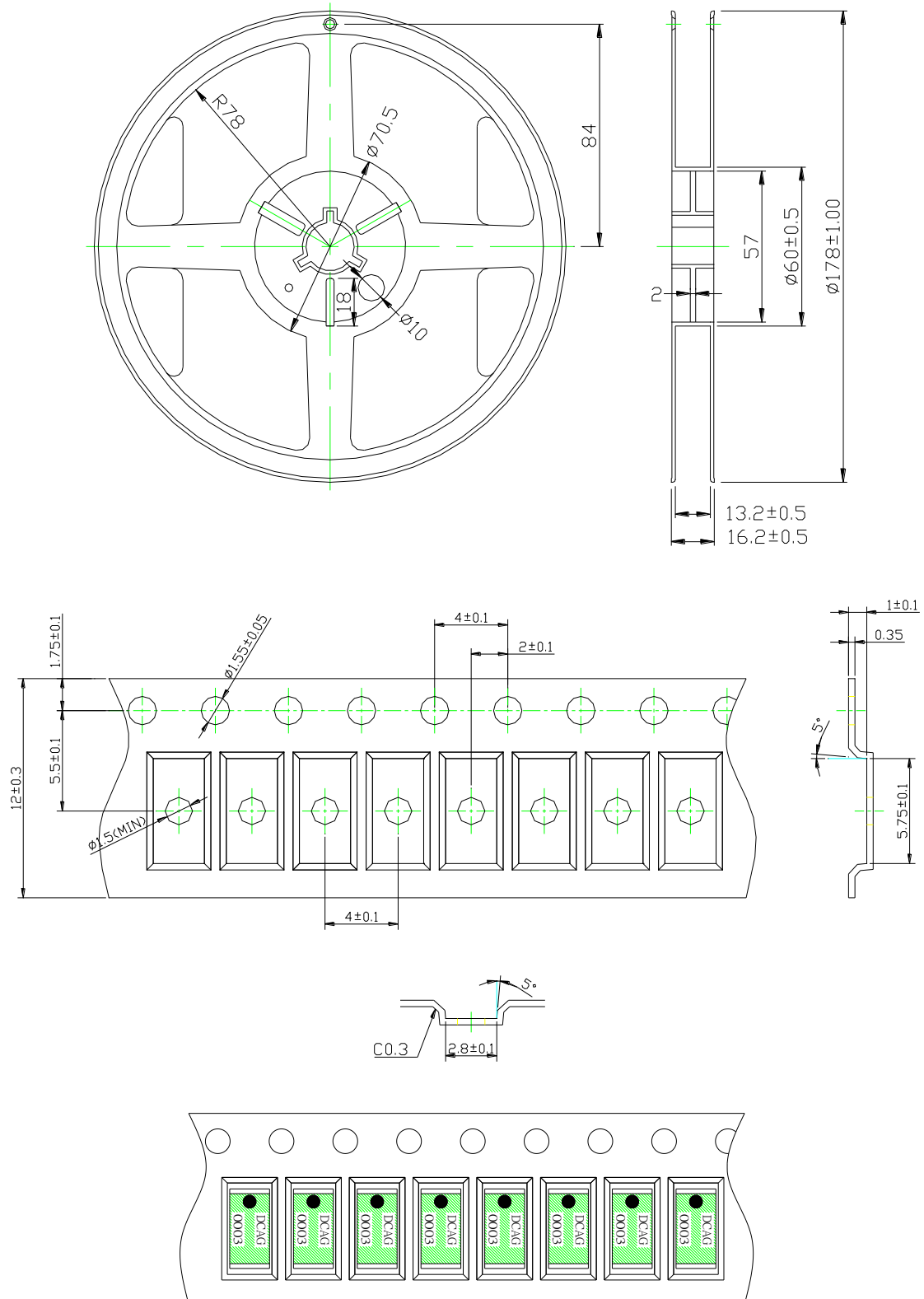
8. Other

Any question arising from this specification manual shall be solved by arrangement made by both parties.

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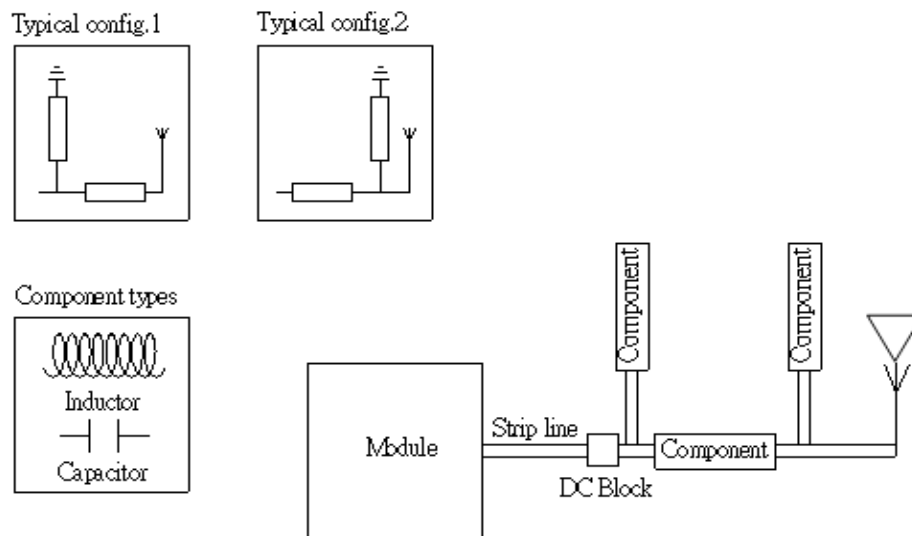
9. Delivery mode

1. Blister tape to IEC 286-3 , polyester .
- 2 .Pieces/tape : 3000pcs.



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10. Transmission line and matching



The matching network has to be individually designed using one,two or three components.

11. Recommended Reflow Soldering Profile

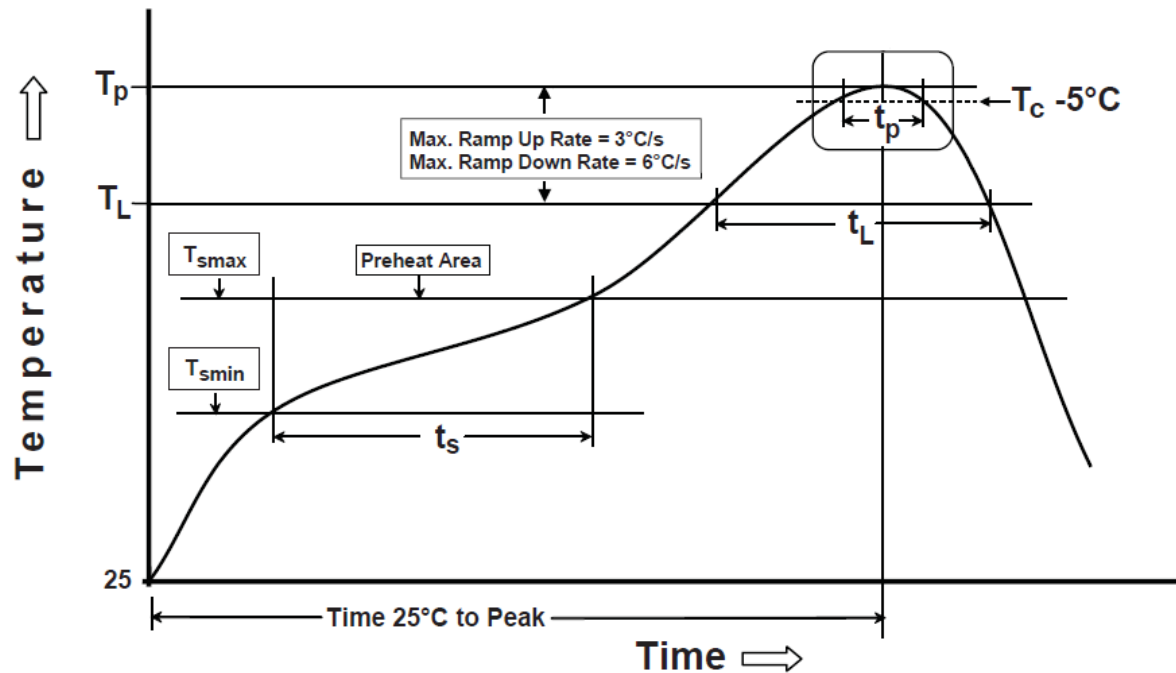
Cirocomm products can be assembled following Pb-free assembly. According to the Standard **IPC/JEDEC J-STD-020C**, the temperature profile suggested is as follow:

Phase	Profile features	Pb-Free Assembly (SnAgCu)
PREHEAT	-Temperature Min(Tsmin) -Temperature Max(Tsmax) -Time(ts) form (Tsmin to Tsmax)	150°C 200°C 60-120 seconds
RAMP-UP	Avg. Ramp-up Rate (Tsmax to TP)	3°C/second(max)
REFLOW	-Temperature(TL) -Total Time above TL (t L)	217°C 30-100 seconds
PEAK	-Temperature(TP) -Time(tp)	260°C 5-10 second
RAMP-DOWN	Rate	6°C / second max.
Time from 25°C to Peak Temperature		8 minutes max.
Composition of solder paste		96.5Sn/3Ag/0.5Cu
Solder Paste Model		SHENMAO PF606-P26

Note : All the temperature measure point is on top surface of the component, if temperature over recommend, it will make component surface peeling or damage.

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The graphic shows temperature profile for component assembly process in reflow ovens



Soldering With Iron:

Soldering condition : Soldering iron temperature $270 \pm 10^\circ\text{C}$.

Apply preheating at 120°C for 2-3 minutes. Finish soldering for each terminal within 3 seconds, if soldering iron over temperature $270 \pm 10^\circ\text{C}$ or 3 seconds, it will make component surface peeling or damage. Soldering iron can not leakage of electricity.